

EVIDENCE OF DRAWING COMPLIANCE IN SUBCONTRACT CCAs

1.0 Definition of terms:

1.0.1 The term “shall”, “will” and “may” are used with specific intent thought-out these documents and will observe the following rules:

- 1.1** Requirements defined using “**shall**” in the text are mandatory requirements and are considered to be binding and require formal verification. Departure from such a requirement is not permissible without formal agreement between Subcontractor and CSPI.
- 1.2** Requirements defined using “**will**” in the text expresses a provision or service by CSPI or an intention by CSPI in connection with a requirement of this document. The subcontractor is implicitly authorized to rely on such service or intention.
- 1.3** The word “**may**” in the text expresses a permissible practice or action. It does not express a requirement of this document.

2.0 Evidence of Drawing Compliance in Subcontract CCA’s

- 2.1** Supplier will ensure the printed circuit board used in this assembly meets the requirements of the applicable drawing. Supplier will be responsible for flowing down CSPI requirements to all printed circuit board fabricators and monitoring the quality of the panel microsections provided to ensure compliance to drawing requirements.
- 2.2** Supplier will retain the items and be able to provide them to CSPI on demand. Retention will be for three (3) years after the delivery of the last CCA using these boards or as documented in the contract specifications, whichever is longer.
- 2.3** The subcontractor of the Circuit Card Assembly (CCA) will provide a Certificate of Conformance to verify that they have reviewed/inspected the microsections from the first lot of raw printed circuit boards received from each supplier to the required standards and specifications. At a minimum, the following items will be available for CSPI inspection in support of any delivered assemblies.
 - 2.3.1** "A and B" or "A/B" microsections that have been solder floated.
 - 2.3.2** Microsections representing unique features (blind, buried vias, etc.).
 - 2.3.3** Coupon strips representing the microsections above.
 - 2.3.4** Any special coupon strips (impedance, peel strength, wire bond, etc.) that are specified on the master drawing.
- 2.4** If CSPI requests delivery of any of the coupon strips and/or microsections listed above, they will not be returned to the supplier.

This document is an integral part of the purchase order. The revision in effect at the time the purchase order was placed applies.